Programme Matter and Technologies

KALYPSO Systems – Update

Institute for data Processing and electronics (IPE- KIT)



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KALYPSO III: toward real-time beam diagnostic at 10 Mfps

Novel front-end electronics ASIC: "Gotthard- High Rate":

Iow-noise front-end for Si and InGaAs sensors

Up to 10 Mfps @ full occupancy

Novel linear array sensors:

✤512/1024 and 2048 pixels with pitch of 25 µm and Anti-reflective Coating



layers for Near-IR, Near-UV and standard

✤512, 1024 LGAD (Low Gain Avalanche Detector) with pitch 50 µm

KALYPSO Version 2.1

New Gotthard – High Rate



First prototype received Dec, 2016 (UMC CMOS 110 nm):

□ Frame-rate up to 12 Mfps (continuous readout by interleaved integration and readout time)

□ Compatible with different sensors **Si** (*p*-*in*-*n* or *n*-*in*-*p*) and **InGaAs**

□ Fully-differential architecture → high PSRR & CMRR



Measured linearity, integral non linearity (INL) and signal-to-noise ratio of the readout chip, not connected to the external sensor (tested with high-gain setting and a line-rate of 10 MHz.)

Second prototype to be submitted Oct, 2017

Improvement: Fully-differential trapezoidal filter to reduce the electronic noise from sensor and front-end

Charge Sensitive Amplifier (CSA): differential folded-cascode with high open-loop gain > 60 dB to improve the charge collection efficiency and the cross-talk between channels

Correlated Double Sampling (CDS): fully-differential switched capacitor time-variant filter to reduce the noise from front-end

Output buffer: fully-differential which can be directly connected to a differential Analog to Digital Converter (ADC)





Cadence spectre simulation of new filter

KT/C noise from reset MOS



improve the photons absorption

Front- and back-illumination

Sensors with Anti-Reflective Coating (ARC) layers → all photons transmitted into semiconductor (no reflected wave)



Low-Gain Avalanche Detector for "fast" transverse bunch profile Improvement:

 \geq Reduced substrate thickness from 300 µm to 50 µm

 \rightarrow reduced collection time for multi-bunch operation

➢Integrate a small-gain (10 − 30) in a sensor while

maintaining similar noise levels

UTURE BUILT N KNOWLEDGE

>No quenching circuit is necessary



512 pixels @ pitch of 50 µm

(special)